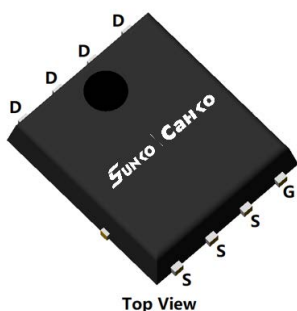
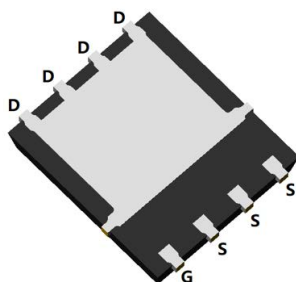


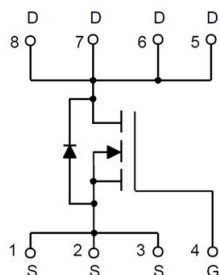
N-Channel Enhancement Mode Field Effect Transistor



Top View



Bottom View



PDFN5060-8L

Product Summary

- V_{DS} 30 V
- I_D 150 A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <2.0 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <3.3 mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Trench Power MV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC-DC Converters
- Power management functions
- Backlighting

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ\text{C}$	I_D	30	A
	$T_A=100^\circ\text{C}$		19	
	$T_C=25^\circ\text{C}$		150	
	$T_C=100^\circ\text{C}$		95	
Pulsed Drain Current ^A		I_{DM}	400	A
Total Power Dissipation ^B	$T_A=25^\circ\text{C}$	P_D	2.7	W
	$T_A=100^\circ\text{C}$		1	
	$T_C=25^\circ\text{C}$		69	
	$T_C=100^\circ\text{C}$		27.6	
Single Pulse Avalanche Energy ^D		E_{AS}	400	mJ
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	1.8	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Ambient ^C		$R_{\theta JA}$	46.5	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCG150N03A	F1	SCG150N03A	5000	10000	100000	13" reel

SCG150N03A

■ Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D =20A		1.58	2.0	mΩ
		V _{GS} = 4.5V, I _D =20A		2.6	3.3	
Diode Forward Voltage	V _{SD}	I _S =20A,V _{GS} =0V		0.75	1.2	V
Maximum Body-Diode Continuous Current	I _S				150	A
Gate resistance	R _g	f=1 MHz		2.9		Ω
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V,f=1MHZ		4498		pF
Output Capacitance	C _{oss}			800		
Reverse Transfer Capacitance	C _{rss}			643		
Switching Parameters						
Total Gate Charge	Q _g (10V)	V _{GS} =10V,V _{DS} =15V,I _D =20A		92.7		nC
Total Gate Charge	Q _g (4.5V)			46		
Gate-Source Charge	Q _{gs}			13.5		
Gate-Drain Charge	Q _{gd}			22.8		
Reverse Recovery Charge	Q _{rr}	I _F =20A, di/dt=500A/us		3.0		ns
Reverse Recovery Time	t _{rr}			15		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =20V, I _D =4A,R _L =0.75Ω R _{GEN} =3Ω		11		
Turn-on Rise Time	t _r			80		
Turn-off Delay Time	t _{D(off)}			39		
Turn-off fall Time	t _f			92		

- A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.
- B. The power dissipation P_D is based on T_{J(MAX)}=150℃, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- C. The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25℃.
- D. T_J=25℃, V_{DD}=30V, V_G=10V, L=2.0mH, I_{AS}=20A

■ Typical Performance Characteristics

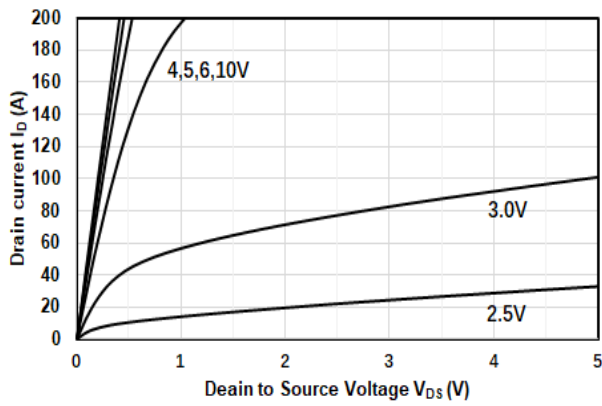


Figure1. Output Characteristics

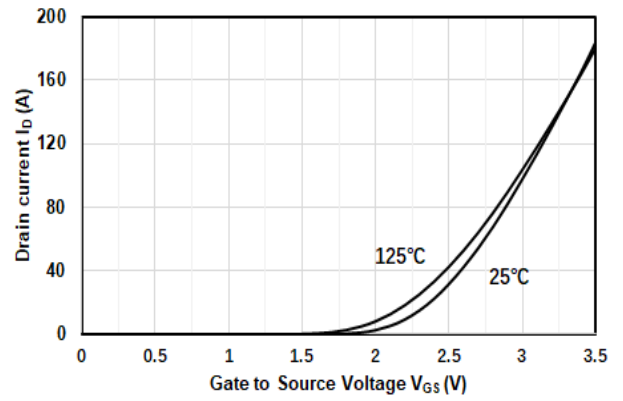


Figure2. Transfer Characteristics

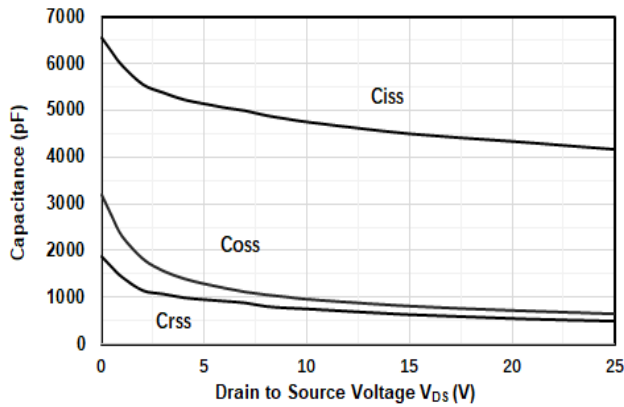


Figure3. Capacitance Characteristics

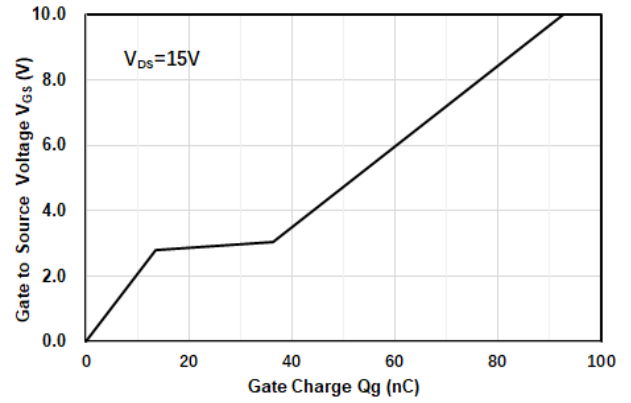


Figure4. Gate Charge

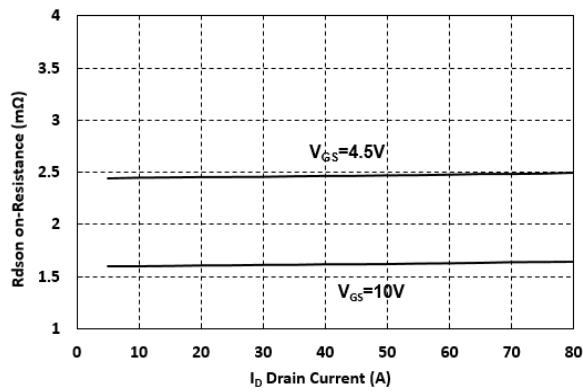


Figure5. Drain-Source on Resistance

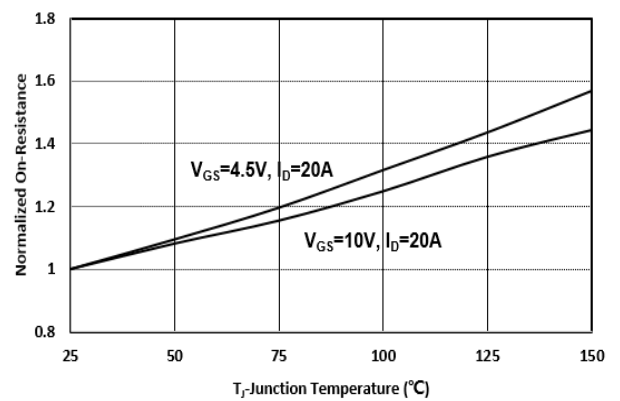


Figure6. Drain-Source on Resistance

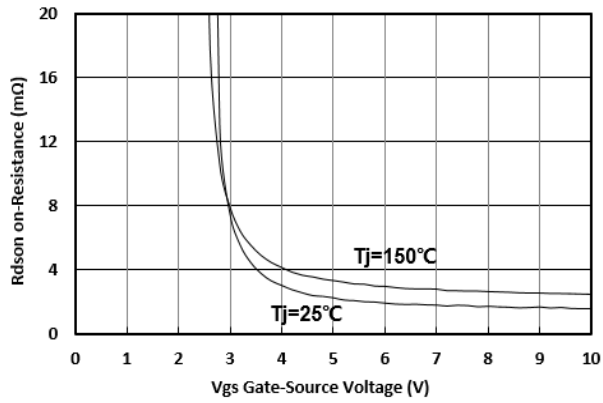


Figure7. On-Resistance vs V_{GS}

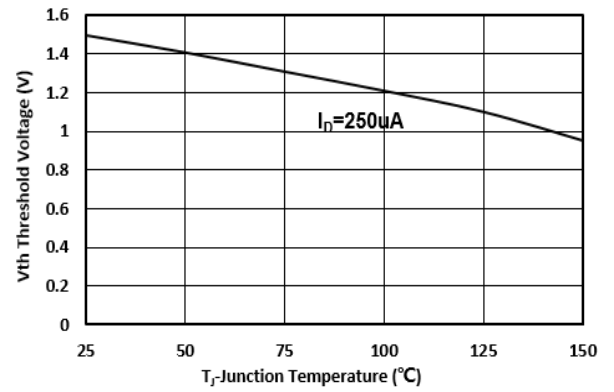


Figure8. V_{th} vs Temperature

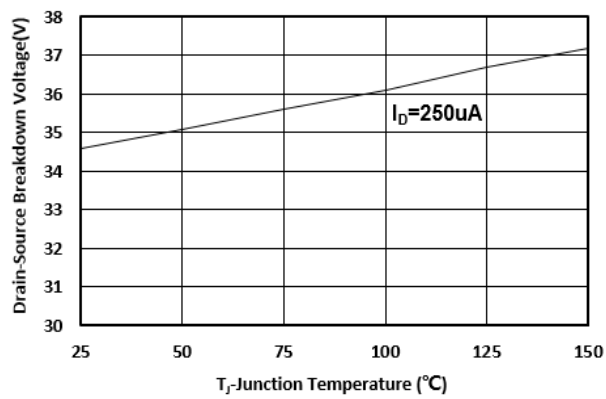


Figure9. Breakdown Voltage vs Temperature

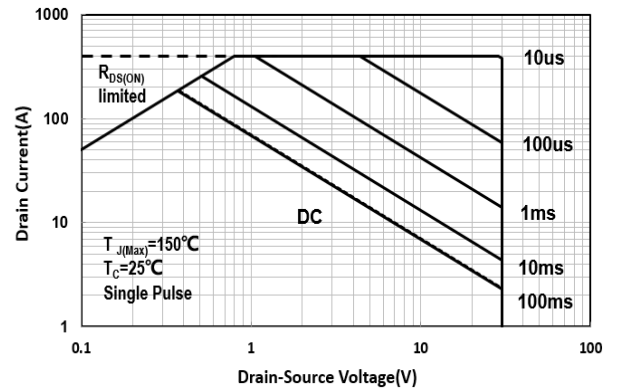


Figure10. Safe Operation Area

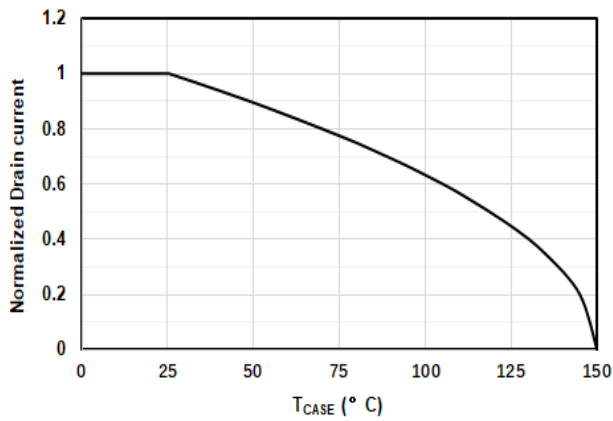


Figure11. Drain current vs. Case Temperature

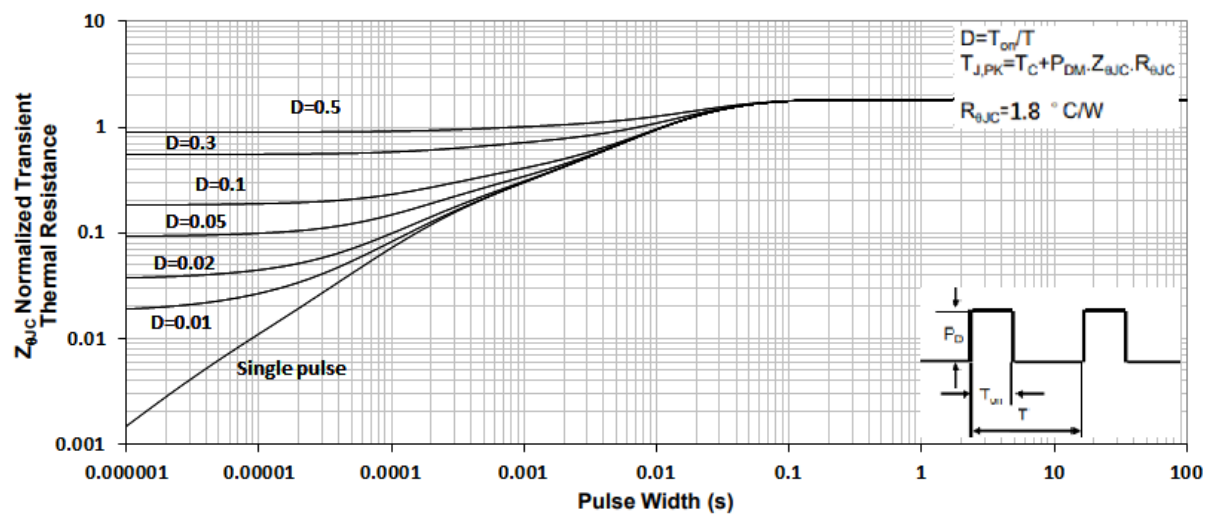
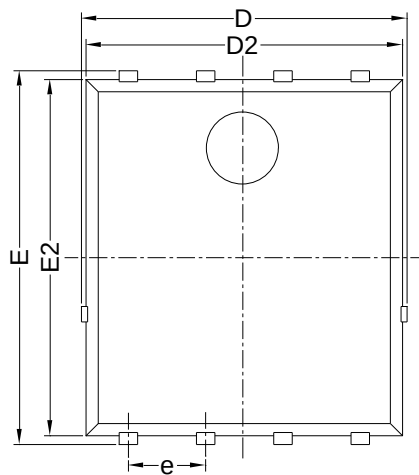
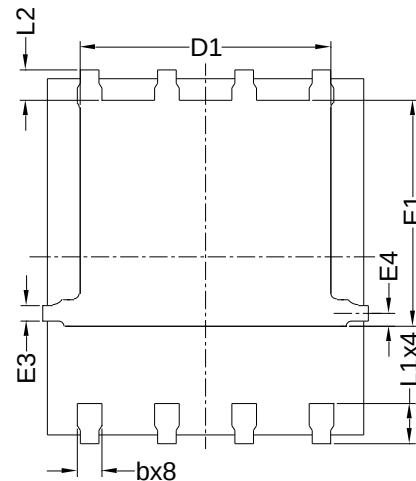


Figure12. Normalized Maximum Transient Thermal Impedance

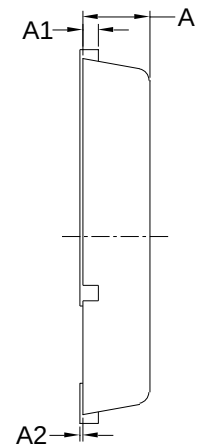
■ PDFN5060-8L-B-1.1MM Package Information



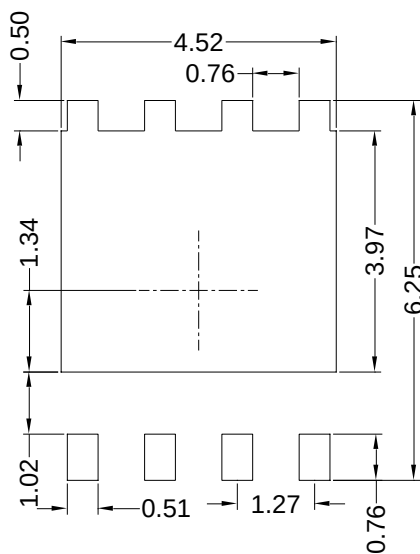
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254 REF		
E4	0.21 REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.

Disclaimer

The information presented in this document is for reference only. Shanghai Sunco Electronics Co., Ltd Reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Russiansunco or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website [http:// www.russiansunco.com](http://www.russiansunco.com) or consult your nearest Russiansunco's sales office for further assistance.